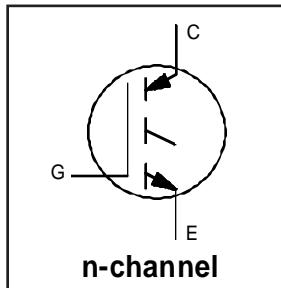


INSULATED GATE BIPOLAR TRANSISTOR

Short Circuit Rated
UltraFast Fast IGBT

Features

- Short circuit rated - 10 μ s @ 125°C, $V_{GE} = 15V$
- Switching-loss rating includes all "tail" losses
- Optimized for high operating frequency (over 5kHz) See Fig. 1 for Current vs. Frequency curve

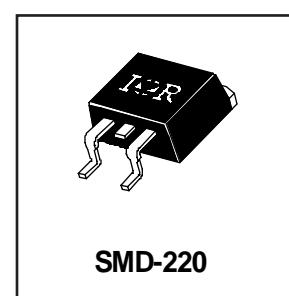


$V_{CES} = 600V$
 $V_{CE(sat)} \leq 3.5V$
 @ $V_{GE} = 15V, I_C = 6.0A$

Description

Insulated Gate Bipolar Transistors (IGBTs) from International Rectifier have higher usable current densities than comparable bipolar transistors, while at the same time having simpler gate-drive requirements of the familiar power MOSFET. They provide substantial benefits to a host of high-voltage, high-current applications.

These new short circuit rated devices are especially suited for motor control and other applications requiring short circuit withstand capability.



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_c = 25^\circ C$	Continuous Collector Current	10	A
$I_C @ T_c = 100^\circ C$	Continuous Collector Current	6.0	
I_{CM}	Pulsed Collector Current ①	20	
I_{LM}	Clamped Inductive Load Current ②	20	
t_{sc}	Short Circuit Withstand Time	10	μ s
V_{GE}	Gate-to-Emitter Voltage	± 20	V
E_{ARV}	Reverse Voltage Avalanche Energy ③	5.0	mJ
$P_D @ T_c = 25^\circ C$	Maximum Power Dissipation	60	W
$P_D @ T_c = 100^\circ C$	Maximum Power Dissipation	24	
T_j T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ$ C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting torque, 6-32 or M3 screw.	10 lbf \cdot in (1.1N \cdot m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	-----	-----	2.1	$^\circ$ C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB mount)**	-----	-----	40	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	-----	-----	80	
Wt	Weight	-----	2 (0.07)	-----	g (oz)

** When mounted on 1" square PCB (FR-4 or G-10 Material)

For recommended footprint and soldering techniques refer to application note #AN-994.

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{CES}}$	Collector-to-Emitter Breakdown Voltage	600	----	----	V	$V_{\text{GE}} = 0\text{V}, I_C = 250\mu\text{A}$
$V_{(\text{BR})\text{ECS}}$	Emitter-to-Collector Breakdown Voltage	② 20	----	----	V	$V_{\text{GE}} = 0\text{V}, I_C = 1.0\text{A}$
$\Delta V_{(\text{BR})\text{CES}/\Delta T_J}$	Temperature Coeff. of Breakdown Voltage	----	0.37	----	V/ $^\circ\text{C}$	$V_{\text{GE}} = 0\text{V}, I_C = 1.0\text{mA}$
$V_{\text{CE}(\text{on})}$	Collector-to-Emitter Saturation Voltage	----	2.4	3.5	V	$I_C = 6.0\text{A}$ $V_{\text{GE}} = 15\text{V}$
		----	3.6	----		$I_C = 10\text{A}$ See Fig. 2, 5
		----	2.9	----		$I_C = 6.0\text{A}, T_J = 150^\circ\text{C}$
		3.0	----	5.5		$V_{\text{CE}} = V_{\text{GE}}, I_C = 250\mu\text{A}$
$\Delta V_{\text{GE}(\text{th})/\Delta T_J}$	Temperature Coeff. of Threshold Voltage	----	-11	----	mV/ $^\circ\text{C}$	$V_{\text{CE}} = V_{\text{GE}}, I_C = 250\mu\text{A}$
g_{fe}	Forward Transconductance ⑤	1.9	3.3	----	S	$V_{\text{CE}} = 100\text{V}, I_C = 6.0\text{A}$
I_{CES}	Zero Gate Voltage Collector Current	----	----	250	μA	$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}$
		----	----	1000		$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}, T_J = 150^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	----	----	± 100	nA	$V_{\text{GE}} = \pm 20\text{V}$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	----	17	26	nC	$I_C = 6.0\text{A}$
Q_{ge}	Gate - Emitter Charge (turn-on)	----	4.3	6.8		$V_{\text{CC}} = 400\text{V}$ See Fig. 8
Q_{gc}	Gate - Collector Charge (turn-on)	----	6.4	11		$V_{\text{GE}} = 15\text{V}$
$t_{d(\text{on})}$	Turn-On Delay Time	----	29	----	ns	$T_J = 25^\circ\text{C}$
t_r	Rise Time	----	18	----		$I_C = 6.0\text{A}, V_{\text{CC}} = 480\text{V}$
$t_{d(\text{off})}$	Turn-Off Delay Time	----	58	90		$V_{\text{GE}} = 15\text{V}, R_G = 50\Omega$
t_f	Fall Time	----	120	195		Energy losses include "tail"
E_{on}	Turn-On Switching Loss	----	0.11	----	mJ	See Fig. 9, 10, 11, 14
E_{off}	Turn-Off Switching Loss	----	0.13	----		
E_{ts}	Total Switching Loss	----	0.24	0.31		
t_{sc}	Short Circuit Withstand Time	10	----	----	μs	$V_{\text{CC}} = 360\text{V}, T_J = 125^\circ\text{C}$ $V_{\text{GE}} = 15\text{V}, R_G = 50\Omega, V_{\text{CPK}} < 500\text{V}$
$t_{d(\text{on})}$	Turn-On Delay Time	----	28	----	ns	$T_J = 150^\circ\text{C},$ $I_C = 6.0\text{A}, V_{\text{CC}} = 480\text{V}$
t_r	Rise Time	----	22	----		$V_{\text{GE}} = 15\text{V}, R_G = 50\Omega$
$t_{d(\text{off})}$	Turn-Off Delay Time	----	200	----		Energy losses include "tail"
t_f	Fall Time	----	145	----		See Fig. 10, 14
E_{ts}	Total Switching Loss	----	0.50	----	mJ	
L_E	Internal Emitter Inductance	----	7.5	----	nH	Measured 5mm from package
C_{ies}	Input Capacitance	----	360	----	pF	$V_{\text{GE}} = 0\text{V}$
C_{oes}	Output Capacitance	----	45	----		$V_{\text{CC}} = 30\text{V}$ See Fig. 7
C_{res}	Reverse Transfer Capacitance	----	4.7	----		$f = 1.0\text{MHz}$

Notes:

- ① Repetitive rating; $V_{\text{GE}}=20\text{V}$, pulse width limited by max. junction temperature.
(See fig. 13b)
- ② $V_{\text{CC}}=80\%(V_{\text{CES}})$, $V_{\text{GE}}=20\text{V}$, $L=10\mu\text{H}$, $R_G=50\Omega$, (See fig. 13a)
- ③ Repetitive rating; pulse width limited by maximum junction temperature.
- ④ Pulse width $\leq 80\mu\text{s}$; duty factor $\leq 0.1\%$.
- ⑤ Pulse width $5.0\mu\text{s}$, single shot.

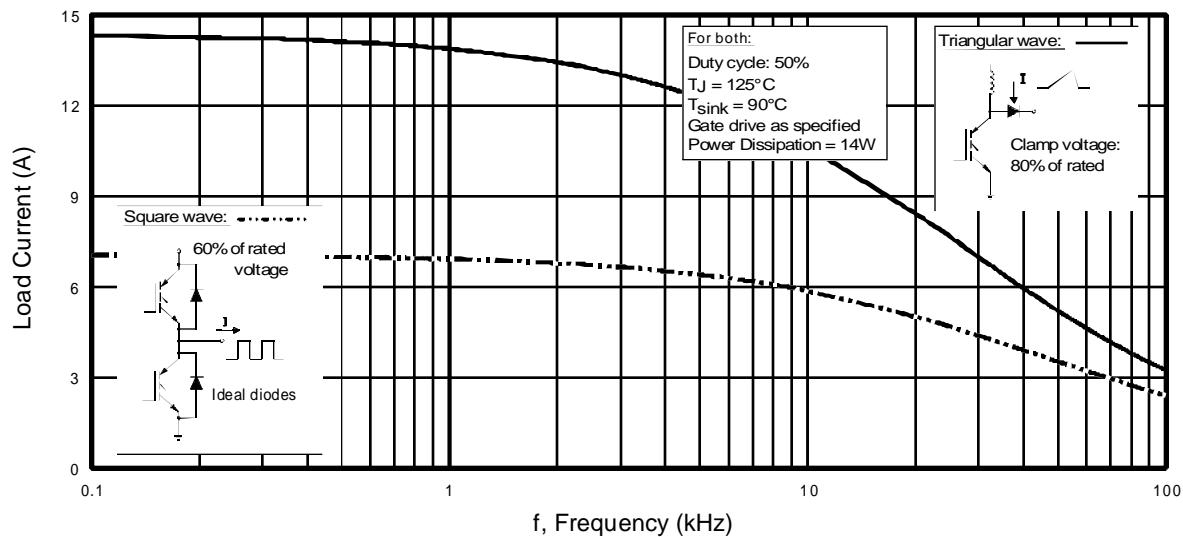


Fig. 1 - Typical Load Current vs. Frequency
(For square wave, $I=I_{RMS}$ of fundamental; for triangular wave, $I=I_{PK}$)

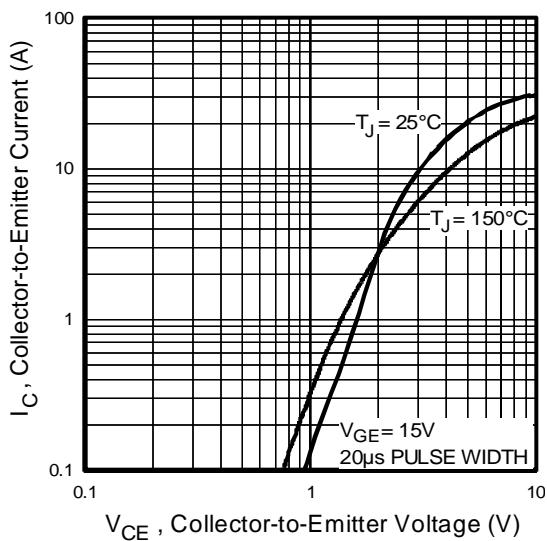


Fig. 2 - Typical Output Characteristics

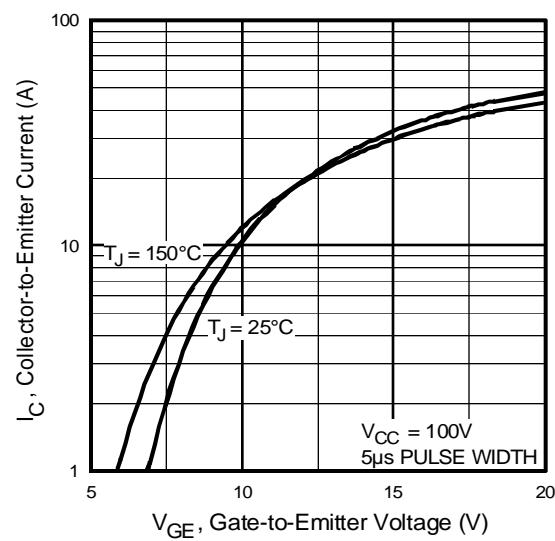


Fig. 3 - Typical Transfer Characteristics

IRGBC20K-S

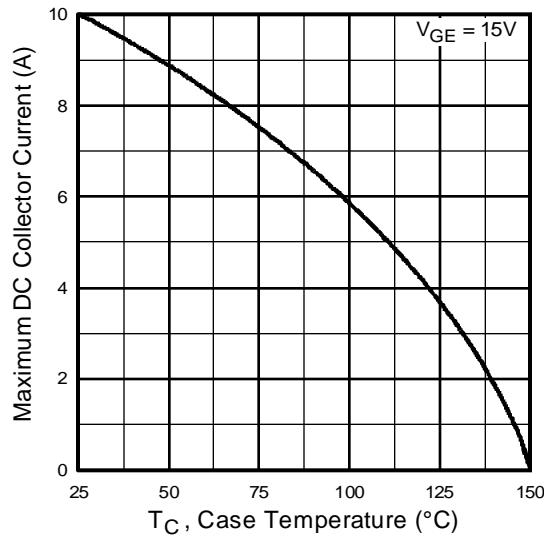


Fig. 4 - Maximum Collector Current vs. Case Temperature

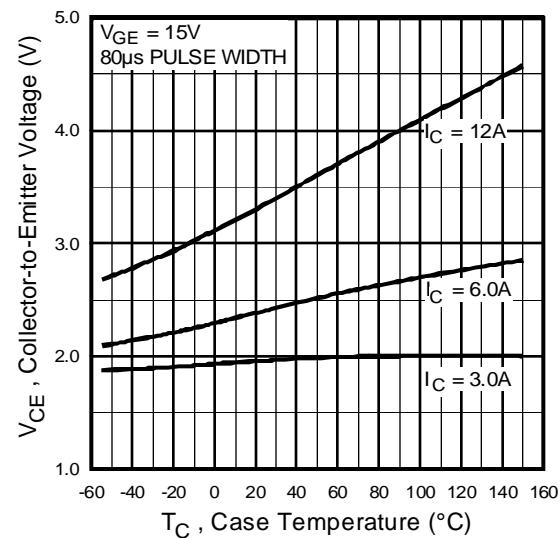


Fig. 5 - Collector-to-Emitter Voltage vs. Case Temperature

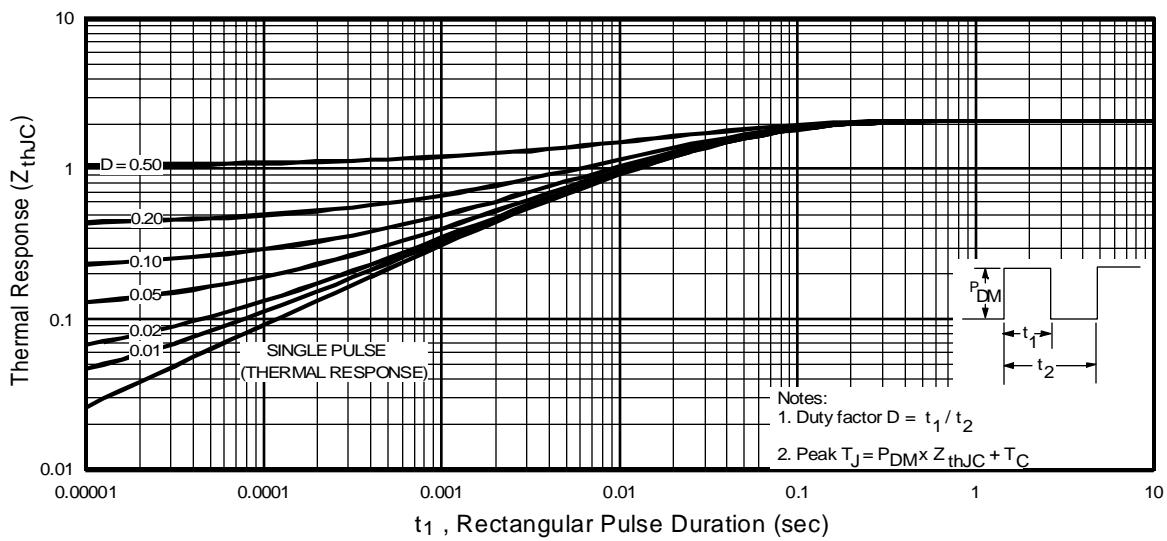


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

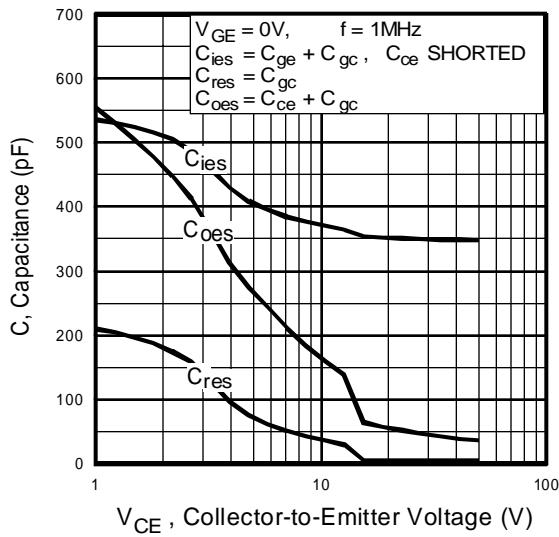


Fig. 7 - Typical Capacitance vs.
Collector-to-Emitter Voltage

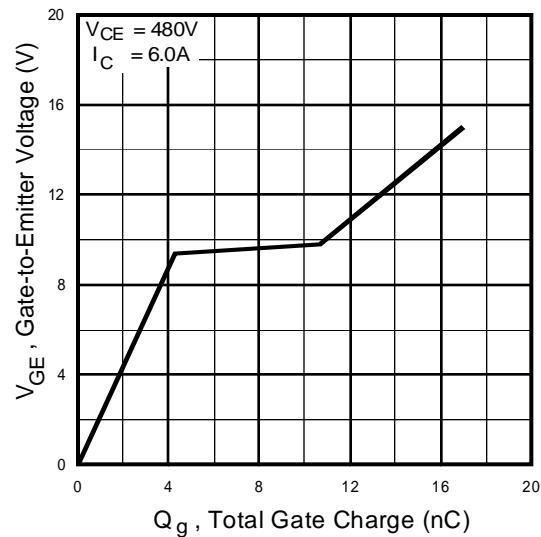


Fig. 8 - Typical Gate Charge vs.
Gate-to-Emitter Voltage

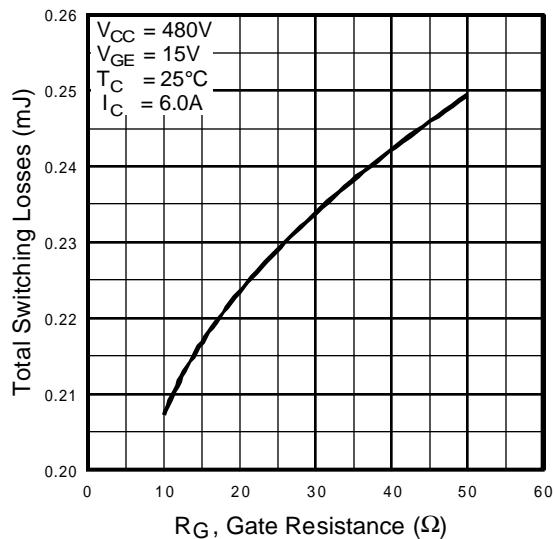


Fig. 9 - Typical Switching Losses vs. Gate
Resistance

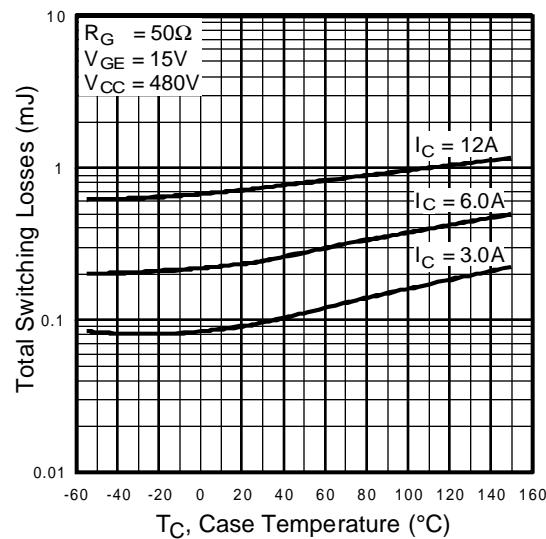


Fig. 10 - Typical Switching Losses vs.
Case Temperature

IRGBC20K-S

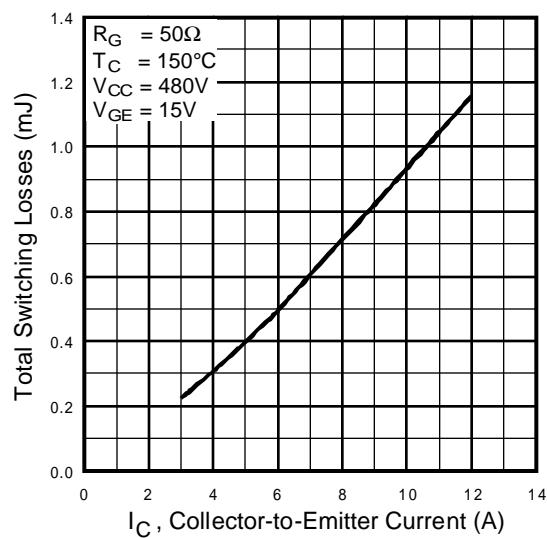


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

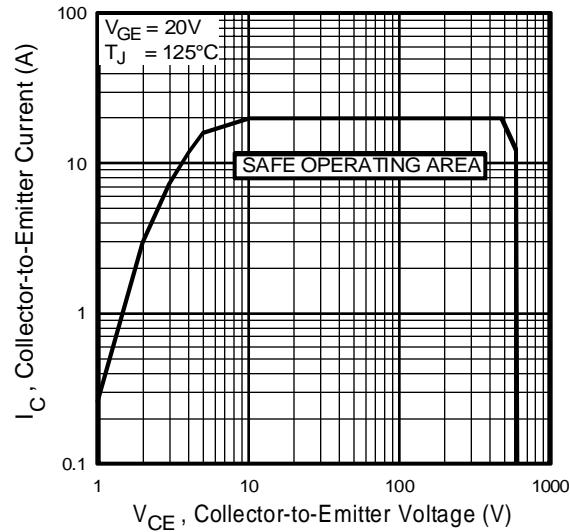
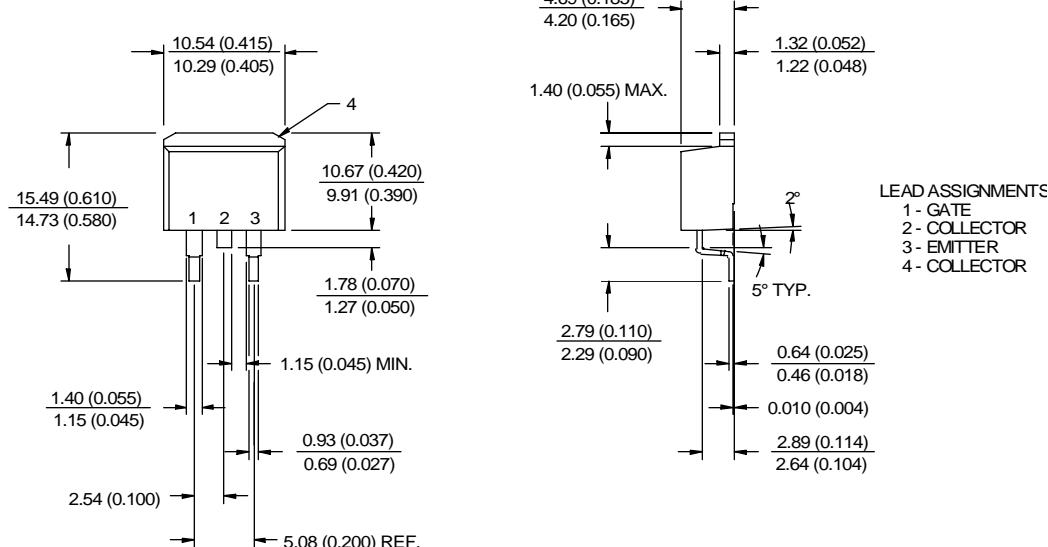
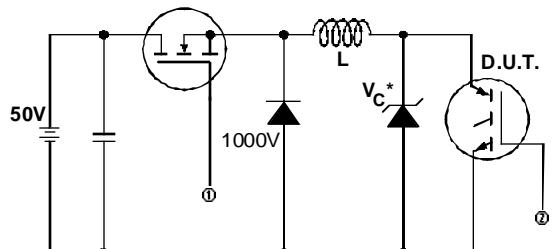


Fig. 12 - Turn-Off SOA



OUTLINE SMD-220

Dimensions in Millimeters and (Inches)



* Driver same type as D.U.T.; $V_C = 80\%$ of $V_{ce(max)}$
 * Note: Due to the 50V power supply, pulse width and inductor will increase to obtain rated I_d .

Fig. 13a - Clamped Inductive Load Test Circuit

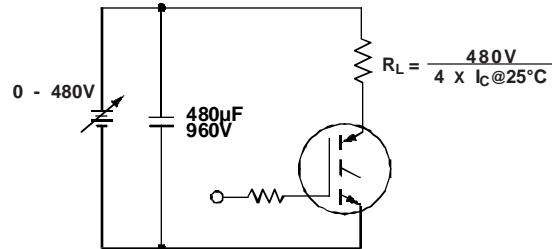


Fig. 13b - Pulsed Collector Current Test Circuit

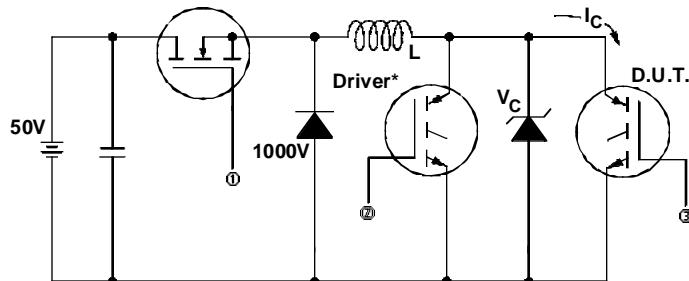


Fig. 14a - Switching Loss Test Circuit

* Driver same type as D.U.T., $V_C = 480V$

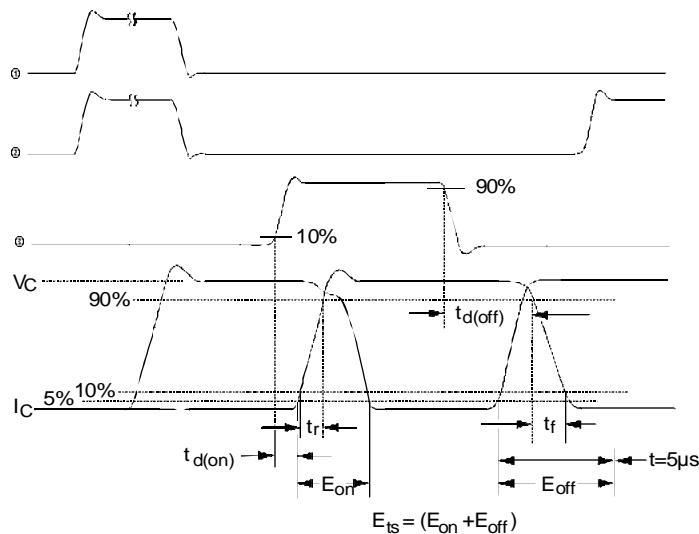


Fig. 14b - Switching Loss Waveforms